3．1 Slion Dicing Tape series (for Wafer)

Item No. All Expandable type		6360-00	6360-20	6360-30	6360-40	6360-50	6360-80	6330-00
UV / non-UV		UV						Non-UV
Thickness (μm) Liner : 38 μm	Backing	PO (90)	PO (90)	PO (90)	PO (90)	PO (90)	PO (100)	PO (90)
	Adhesive	10	10	10	10	10	10	10
	Total	100	100	100	100	100	110	100
Peeling Strength: (N/10mm) (After UV)	SUS	2.5 (0.16)	3.3 (0.18)	2.5 (0.12)	2.4 (0.18)	2.7 (0.12)	0.75 (0.04)	0.39
	Glass	2.3 (0.15)	3.2 (0.25)	2.5 (0.16)	3.3 (0.90)	2.5 (0.13)	- -	0.32
	Si Wafer (Mirror)	2.5 (0.15)	3.7 (0.26)	2.7 (0.16)	2.7 (0.20)	2.3 (0.09)	0.85 (0.04)	0.32
Holding Power		<0.1mm	<0.1mm	<0.1mm	<0.1mm	<0.1mm	<0.1mm	<0.1mm
Tensile Strength (TD/MD) – Before UV (N/10mm)		17/20	17/20	17/20	17/20	17/20	11/11	16/18
Elongation (TD/MD) – Before UV (%/10mm)		760/770	760/770	760/770	760/770	760/770	410/450	700/600
Remark (type)		Standard	High Adhesion For chip flying	Short Irradiation	Chipping resistance	Easy pick-up	Excellent Chipping resistance	Standard